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Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild_questions@onsemi.com.

December 2014

FQPF9P25YDTU

P-Channel QFET® MOSFET

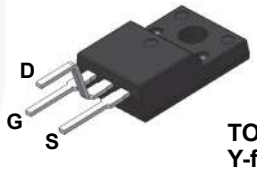
-250 V, -6 A, 620 mΩ

Description

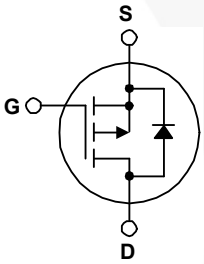
This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

Features

- -6 A, -250 V, $R_{DS(on)}$ = 620 mΩ (Max.) @ V_{GS} = -10 V, I_D = -3 A
- Low Gate Charge (Typ. 29 nC)
- Low Crss (Typ. 27 pF)
- 100% Avalanche Tested



TO-220F
Y-formed



Absolute Maximum Ratings

T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQPF9P25YDTU	Unit
V_{DSS}	Drain-Source Voltage		-250	V
I_D	Drain Current - Continuous (T_C = 25°C)		-6.0	A
	- Continuous (T_C = 100°C)		-3.9	A
I_{DM}	Drain Current - Pulsed	(Note 1)	-24	A
V_{GSS}	Gate-Source Voltage		± 30	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	650	mJ
I_{AR}	Avalanche Current	(Note 1)	-6.0	A
E_{AR}	Repetitive Avalanche Energy	(Note 1)	5.0	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-5.5	V/ns
P_D	Power Dissipation (T_C = 25°C)		50	W
	- Derate above 25°C		0.4	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T_L	Maximum lead temperature for soldering, 1/8" from case for 5 seconds.		300	°C

Thermal Characteristics

Symbol	Parameter	FQPF9P25YDTU	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQPF9P25YDTU	FQPF9P25	TO-220F (Y-formed)	Tube	N/A	N/A	50 units

Electrical Characteristics

T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = -250 μA	-250	--	--	V
ΔBV_{DSS} / ΔT_J	Breakdown Voltage Temperature Coefficient	I_D = -250 μA, Referenced to 25°C	--	-0.2	--	V/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = -250 V, V_{GS} = 0 V	--	--	-1	μA
		V_{DS} = -200 V, T_C = 125°C	--	--	-10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = -30 V, V_{DS} = 0 V	--	--	-100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = 30 V, V_{DS} = 0 V	--	--	100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = -250 μA	-3.0	--	-5.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = -10 V, I_D = -3.0 A	--	0.48	0.62	Ω
g_{FS}	Forward Transconductance	V_{DS} = -40 V, I_D = -3.0 A	--	4.8	--	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = -25 V, V_{GS} = 0 V, f = 1.0 MHz	--	910	1180	pF
C_{oss}	Output Capacitance		--	170	220	pF
C_{rss}	Reverse Transfer Capacitance		--	27	35	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = -125 V, I_D = -9.4 A, R_G = 25 Ω (Note 4)	--	20	50	ns
t_r	Turn-On Rise Time		--	150	310	ns
$t_{d(off)}$	Turn-Off Delay Time		--	45	100	ns
t_f	Turn-Off Fall Time		--	65	140	ns
Q_g	Total Gate Charge	V_{DS} = -200 V, I_D = -9.4 A, V_{GS} = -10 V (Note 4)	--	29	38	nC
Q_{gs}	Gate-Source Charge		--	7.6	--	nC
Q_{gd}	Gate-Drain Charge		--	14	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	-6.0	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	-24	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = -6.0 A	--	--	-5.0	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0 V, I_S = -9.4 A, dI_F / dt = 100 A/μs	--	190	--	ns
Q_{rr}	Reverse Recovery Charge		--	1.45	--	μC

Notes:

1. Repetitive rating : pulse-width limited by maximum junction temperature.
2. L = 28.9 mH, I_{AS} = -6.0 A, V_{DD} = -50 V, R_G = 25 Ω, starting T_J = 25°C.
3. $I_{SD} \leq$ -9.4 A, di/dt $\leq$ 300 A/μs , $V_{DD} \leq BV_{DSS,}$ starting T_J = 25°C.
4. Essentially independent of operating temperature.

Typical Characteristics

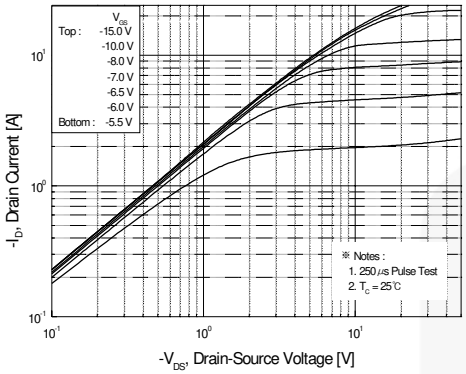


Figure 1. On-Region Characteristics

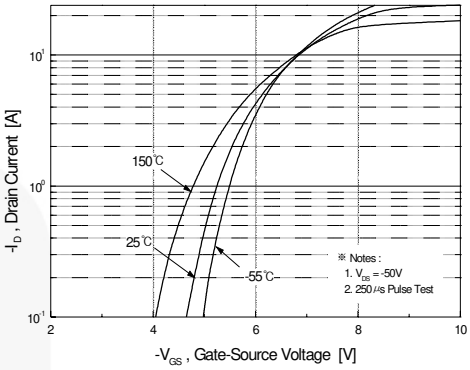


Figure 2. Transfer Characteristics

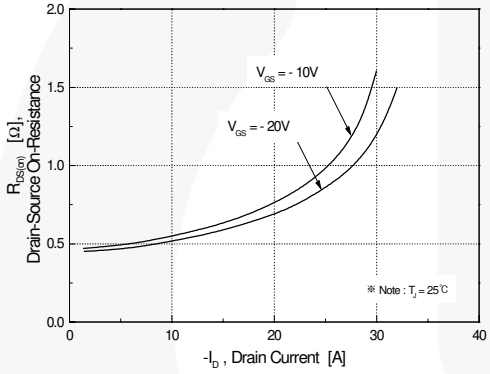


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

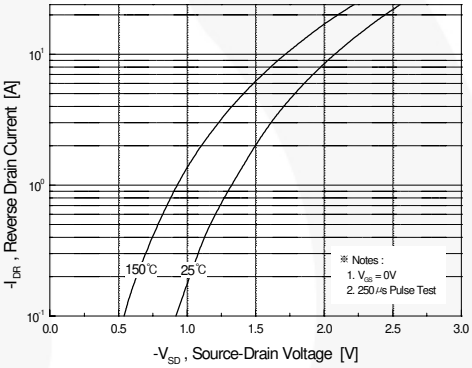


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

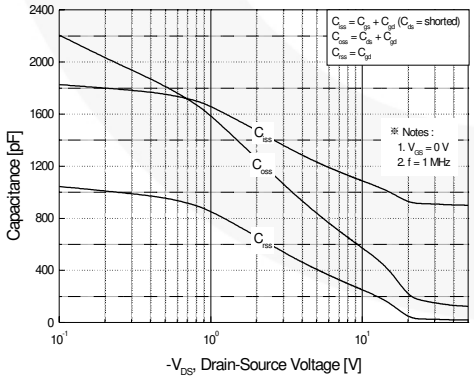


Figure 5. Capacitance Characteristics

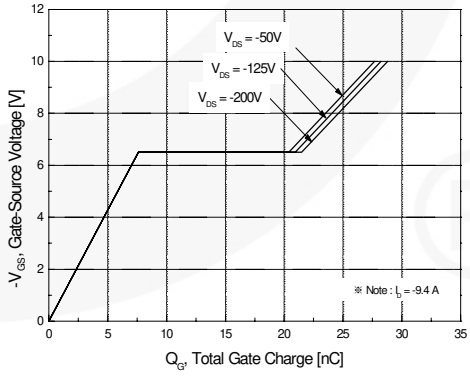


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

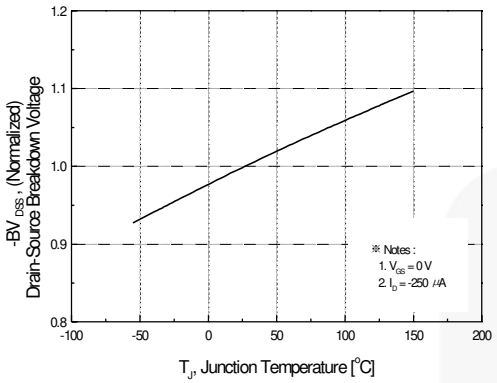


Figure 7. Breakdown Voltage Variation vs. Temperature

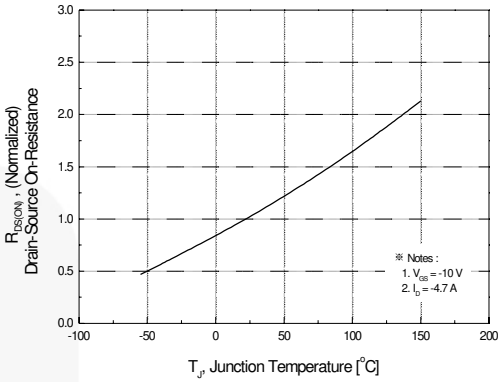


Figure 8. On-Resistance Variation vs. Temperature

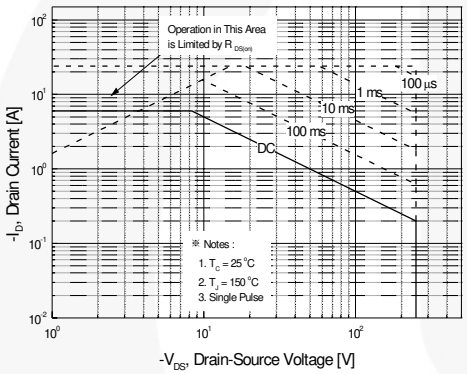


Figure 9. Maximum Safe Operating Area

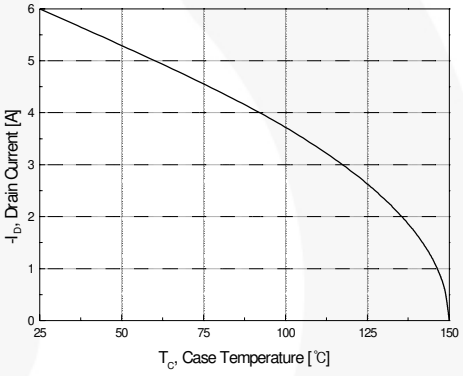


Figure 10. Maximum Drain Current vs. Case Temperature

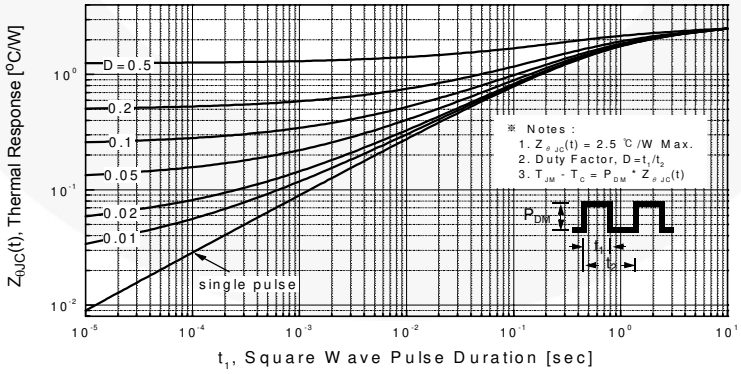


Figure 11. Transient Thermal Response Curve

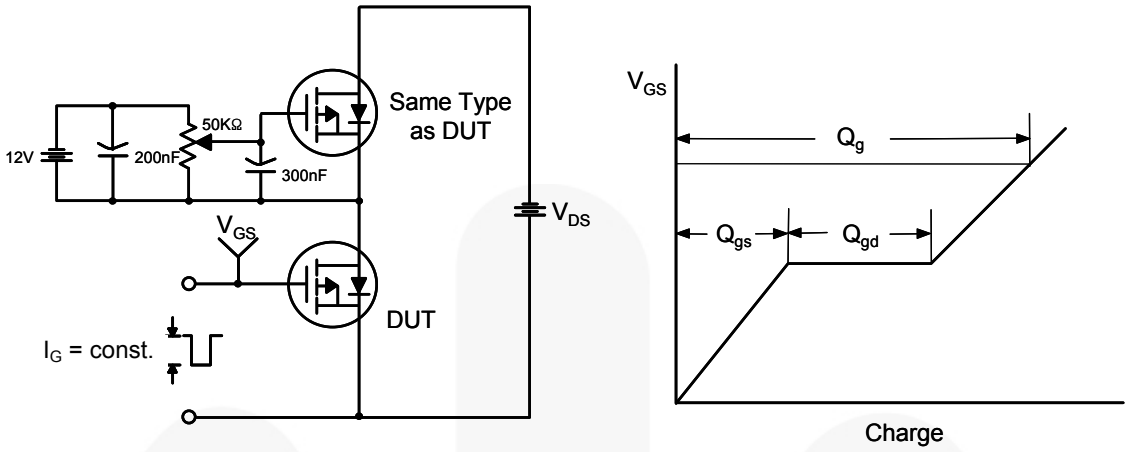


Figure 12. Gate Charge Test Circuit & Waveform

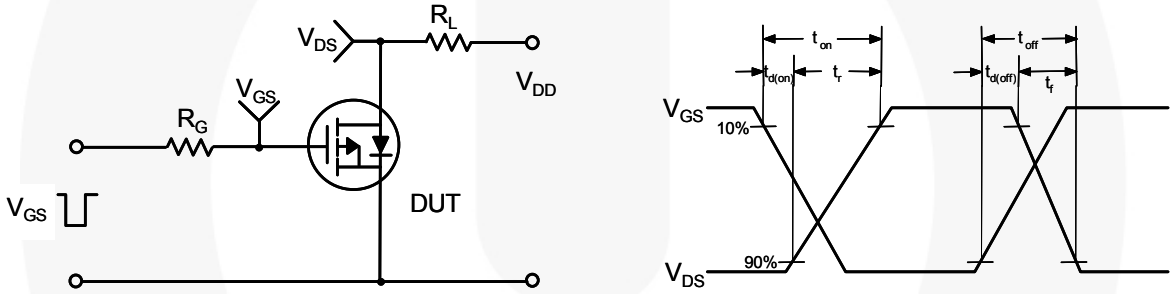


Figure 13. Resistive Switching Test Circuit & Waveforms

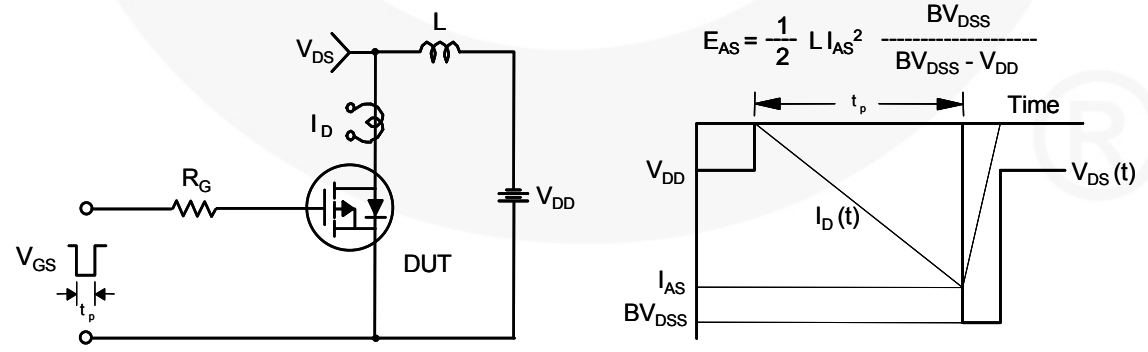


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

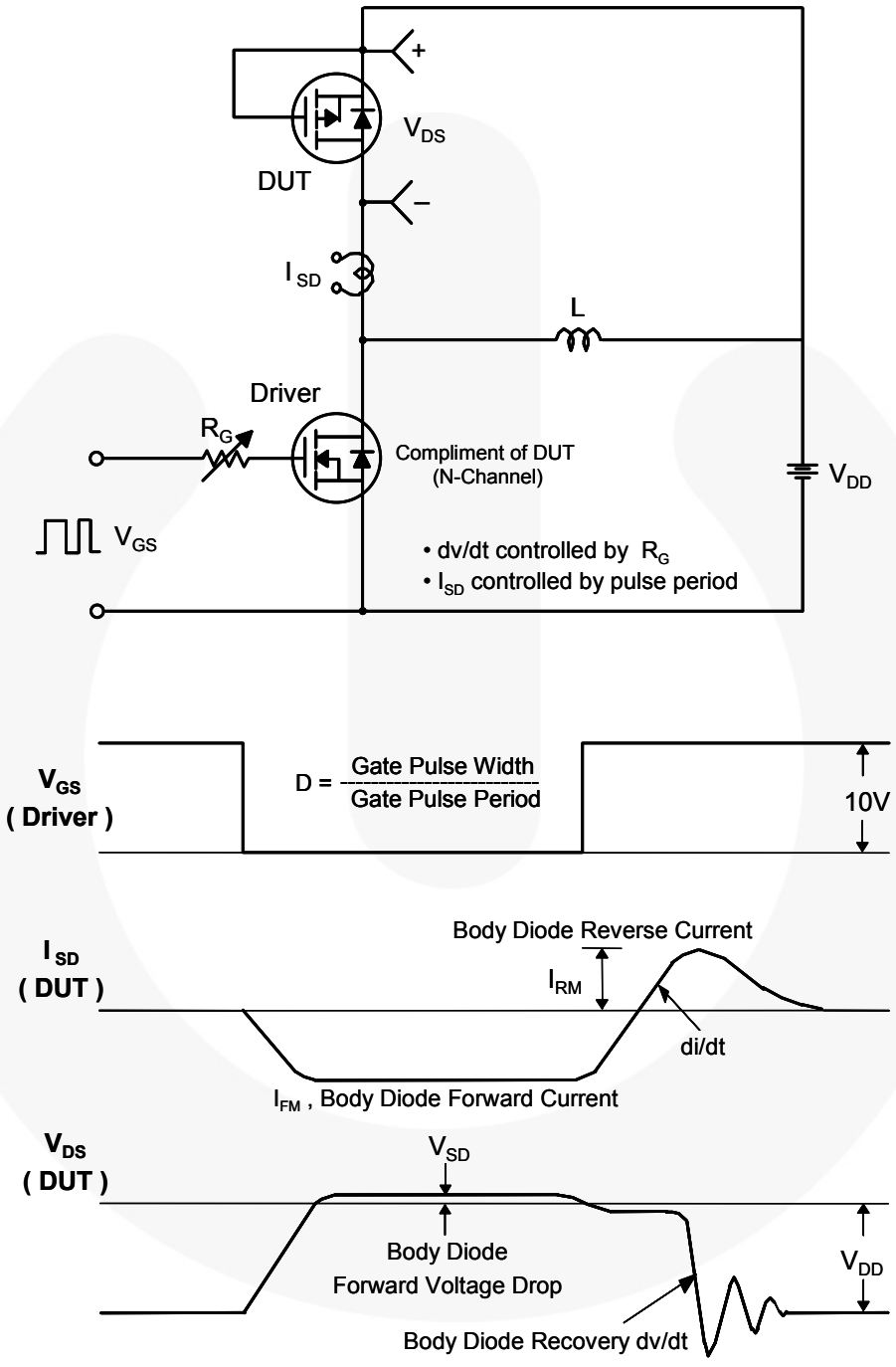
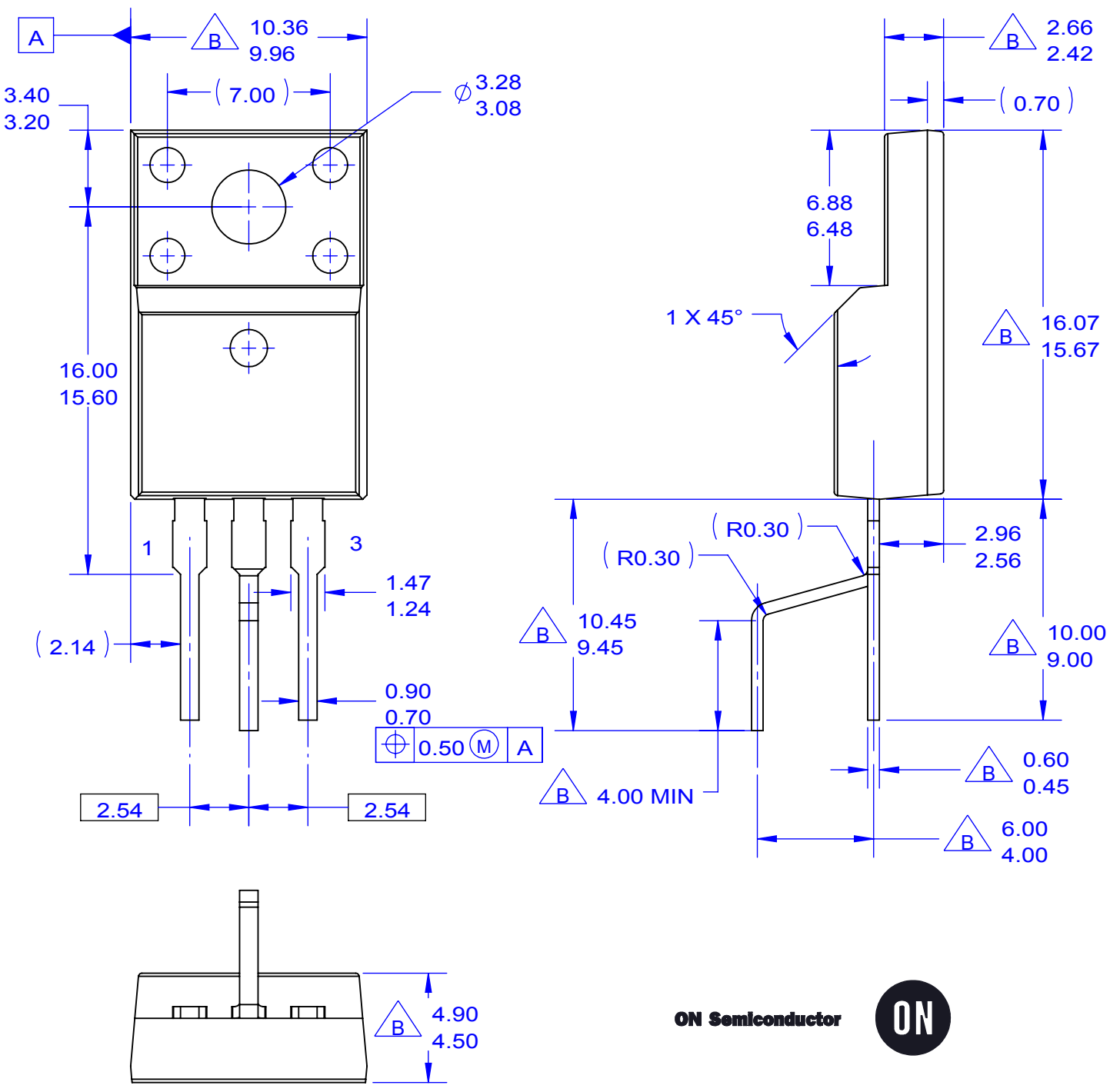


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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NOTES:

A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.
B. DOES NOT COMPLY EIAJ STD. VALUE.
C. ALL DIMENSIONS ARE IN MILLIMETERS.
D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
F. DRAWING FILE NAME: TO220Q03REV2

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